AREA OF INTEREST

Papers in the following areas are invited by the symposium, but papers in other related areas will also be considered:

- Abrasive machining
- · Abrasive jet machining
- · Advanced cutting technology
- · Beam-aided processing
- · Brittle material machining
- CMP and semiconductor wafer processing
- · Coolants and cooling
- Design, fabrication and analysis of devices for the applications of abrasive technologies
- Eco-machining
- · EDM, ultrasonic machining, and laser machining
- · Finishing, lapping, polishing, and deburring
- · Glass molding and related topics
- Grinding wheel and abrasive grain technologies
- · High speed and high-efficiency machining
- In-process measurement and monitoring and metrology
- Machine tools and systems, tooling processing
- · Machining of 3D printed components
- Micro/nano-machining
- Robotic abrasive finishing
- Surface integrity and material characterization
- Tribology in manufacturing
- Truing, dressing, and ELID

IMPORTANT DATES IN 2018

- March 1 Full paper submission to both IJAT and ISAAT
- March 1 Abstract submission to ISAAT only
- March 15 Notification of ISAAT abstract acceptance
- May 1 Full paper submission to ISAAT
- May 31 Notification of ISAAT paper acceptance
- June 15 Submission of final ISAAT paper
- June 30 Payment of early registration fee
- October 14 Conference registration and reception
- October 15-16 Technical sessions
- October 17 Technical visit

SUBMISSION GUIDLINE

- Authors will be provided the options to submit their papers to ISAAT proceedings only, or to both ISAAT proceedings and the International Journal of Abrasive Technology (IJAT, El indexed).
- Abstract submission to ISAAT: The abstract must include paper title, authors and their affiliations, and a summary of the paper within 200 words.
- Full ISAAT papers must be written in English of length from 4 to 6 proceedings pages.
- Each paper must be formatted and submitted according to the Instructions for Authors available in the ISAAT2018 website.

PAPER PRESENTATION & PUBLICATION

All papers will be peer reviewed. Accepted papers MUST be presented in oral or poster session. Each delegate may present up to two papers (a publication fee will be charged for the second paper).

ACCOMMODATION

Information of hotel will be available on the conference website

TRAVEL INFORMATION

Travel information will be available on the conference website.

SYMPOSIUM SECRETARIAT

Gabriel Campos

Email: 2018isaat@gmail.com



Call for Papers ISAAT2018

The 21st International Symposium on Advances in Abrasive Technology
October 14 – 17, 2018
Toronto, Canada



Organized by

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HISTORY & SCOPE

The International Symposium on Advances in Abrasive Technology (ISAAT) was first held in Sydney, Australia in 1997. Since 2002, JSAT and ICAT have been jointly organizing this exciting annual event for this community and the symposia have been successfully held in Hong Kong, UK, Turkey, Russia, US, Japan, Australia, Taiwan, Germany, Singapore, China, Republic of Korea, and Sweden. An emphasis of the ISAAT series is to bring together both academic researchers and industrial practitioners from around the world for the interchange of the latest developments and applications in abrasive technologies. The ISAAT2018 in Toronto Canada will continue to promote the discipline development and research collaboration, and to foster the growth of young engineers and researchers in this field.

REGISTRATION

Full registration US\$700 Student registration US\$500

Late registration US\$800/full registration
After June 30 US\$600/student

A full registration covers the costs of the attendance to all technical sessions, conference proceedings, welcoming reception, banquet and lunches. A student registration does not include the cost of the banquet.

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